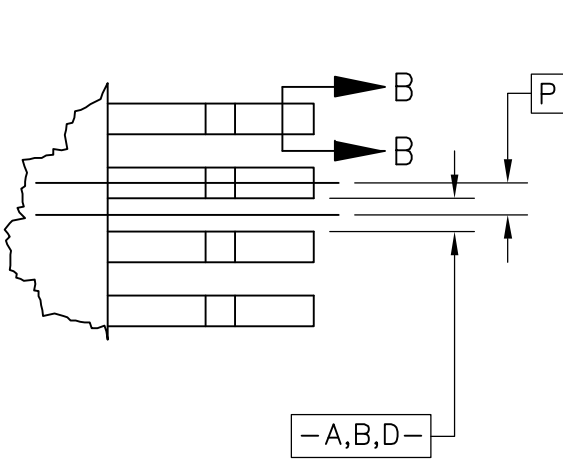
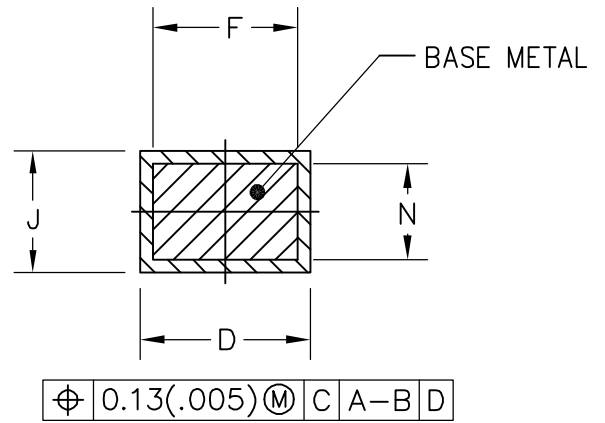


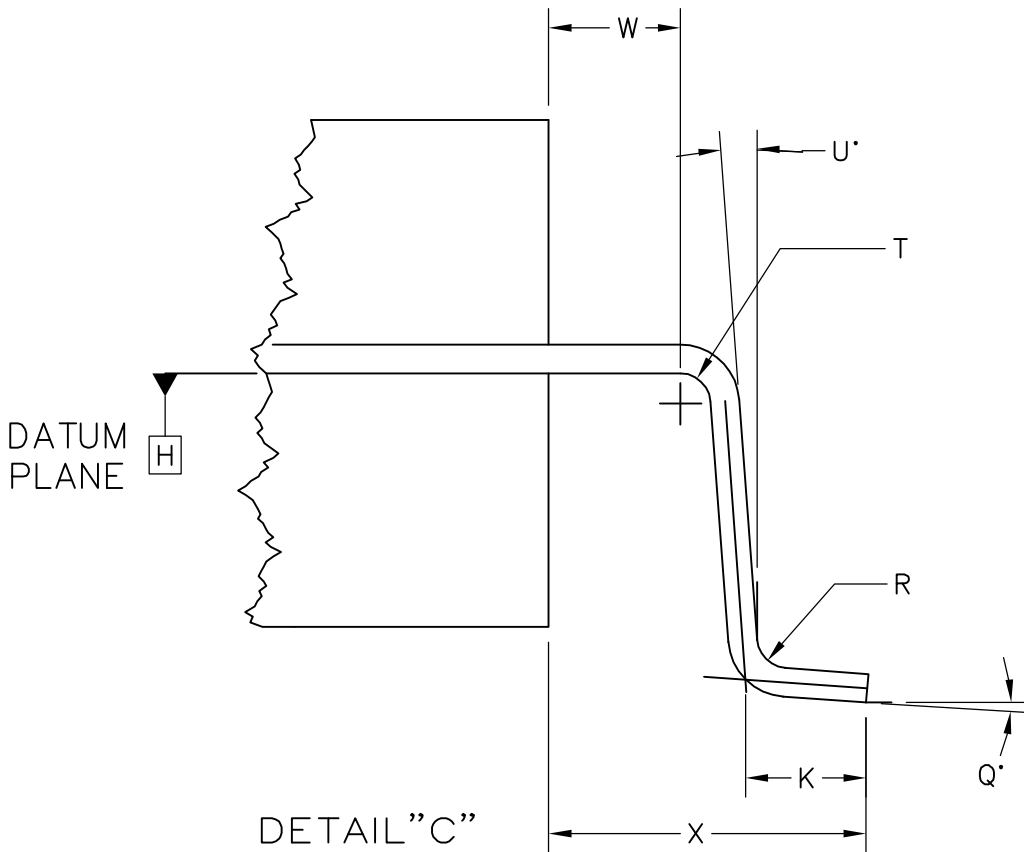
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TITLE: CQFP 144 LEAD 26.77 X 26.77 X 3.5 0.65 MM PITCH	DOCUMENT NO: 98ASB4800B	REV: C
	STANDARD: NON-JEDEC	
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DETAIL A



SECTION B-B



DETAIL "C"

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	STANDARD: NON-JEDEC	
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1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS -A-, -B- AND -D- TO BE DETERMINED AT DATUM PLANE -H-.
5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -C-.
6. DIMENSIONS A AND B DEFINE MAXIMUM CERAMIC BODY DIMENSIONS INCLUDING GLASS PROTRUSION AND MISMATCH CERAMIC BODY TOP AND BOTTOM.

DIM	MILLIMETER		INCH		DIM	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	25.84	27.70	1.017	1.091	Q	0°	8°	0°	8°
B	25.84	27.70	1.017	1.091	R	0.20 REF		0.008 REF	
C	3.55	4.31	0.140	0.170	S	30.95	31.45	1.219	1.238
D	0.22	0.41	0.009	0.016	T	0.20 REF		0.008 REF	
E	2.95	3.70	0.116	0.146	U	0°	8°	0°	8°
F	0.20	0.36	0.008	0.014	V	30.95	31.45	1.219	1.238
G	0.65 BSC		0.026 BSC		W	1.50 REF		0.059 REF	
H	0.25	0.88	0.010	0.035	X	2.50 REF		0.098 REF	
J	0.13	0.25	0.005	0.010	Y	1.60 REF		0.063 REF	
K	0.65	0.95	0.026	0.037	Z	1.60 REF		0.063 REF	
L	22.75 REF		0.896 REF						
N	0.10	0.16	0.004	0.006					
P	0.33 BSC		0.013 BSC						

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